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Electronic Patent Application Submission

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EFS ID: 53070
Application ID: 10669820
Title of Invention: REINFORCED DIE PAD SUPPORT STRUCTURE
First Named Inventor: Chung Tzu
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-09-24
Effective Receipt Date: 2004-01-02
Submission Type: Information Disclosure Statement
Filing Type:
Confirmation number: 5197
Attorney Docket Number: AMKOR090A



Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US

Certificate Message Digest: 4ecf1e4c9720f6b53b9bbd47b725e6975808a0ab



TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE	
Application Number:	10/669820 	
Date:	2003-09-24	
First Named Applicant:	Chung Hsing Tzu	
Confirmation Number:	5197	
Attorney Docket Number:	AMKOR090A	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids5-usidst.xml us-ids.dtd us-ids.xsl	
Comments		

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PATENT & TRADEMARK OFFICE

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE				
Application Number:	10/669820 				
Confirmation Number:	5197				
First Named Applicant:	Chung Tzu				
Attorney Docket Number:	AMKOR090A				
Art Unit:	2811				
Search string:	(6197615 or 6198171 or 6201186 or 6201292 or 6204554 or 6208020 or 6208021 or 6208023 or 6211462 or 6218731 or 6222258 or 6225146 or 6229200 or 6229205 or 6239367 or 6239384 or 6242281 or 6256200 or 6258629 or 6281566 or 6281568 or 6282095 or 6285075 or 6291271 or 6291273 or 6294100 or 6294830 or 6295977 or 6297548 or 6303984 or 6303997 or 6307272 or 6309909 or 6316822 or 6316838 or 6323550 or 6326243 or 6326244 or 6326678 or 6335564 or 6337510 or 6339255 or 6348726 or 6355502 or 6369447 or 6369454 or 6373127 or 6380048 or 6384472 or 6388336).pn.				
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents					
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Signature

Examiner Name	Date